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(12) **United States Design Patent**
Mecchella et al.

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(54) **ELECTRONIC DEVICE COVER**
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(US)

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(*) Notice: This patent is subject to a terminal dis-
claimer.

(**) Term: **14 Years**

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(52) **U.S. Cl.**
USPC **D14/440**

(58) **Field of Classification Search**
CPC ... G06F 1/1601; G06F 1/1626; G06F 1/1633;
G06F 1/1675; G06F 1/1679; G02F 1/1306;
G02F 1/133; G02F 1/133308; G02F 1/153;
G02F 1/1533; G02F 2001/133317; H04M
1/185; H04M 1/0252; H04B 1/3888
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D3/218, 215, 201, 294, 289, 900;
220/4.02; 248/309.1; 361/679.56;
379/426, 433.11, 455; 455/575.1,
455/575.8, 457.1; 190/100; 206/305, 320,
206/45.2; D21/469; 312/240
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

1,370,279 A 3/1921 Burzynski
1,613,536 A * 1/1927 Rose 132/315
2,726,835 A 12/1955 Hummel

D230,376 S 2/1974 Andrew
4,259,568 A * 3/1981 Dynesen 235/1 D
4,318,527 A 3/1982 Smith
6,772,879 B1 * 8/2004 Domotor 206/45.23
7,281,698 B2 * 10/2007 Patterson, Jr. 248/458

(Continued)

OTHER PUBLICATIONS

Translated the Japanese Office Action mailed Aug. 8, 2014 for Japa-
nese design application No. 2014-004977, a counterpart foreign
application of design U.S. Appl. No. 29/467,672, 3 pages.

(Continued)

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(57) **CLAIM**

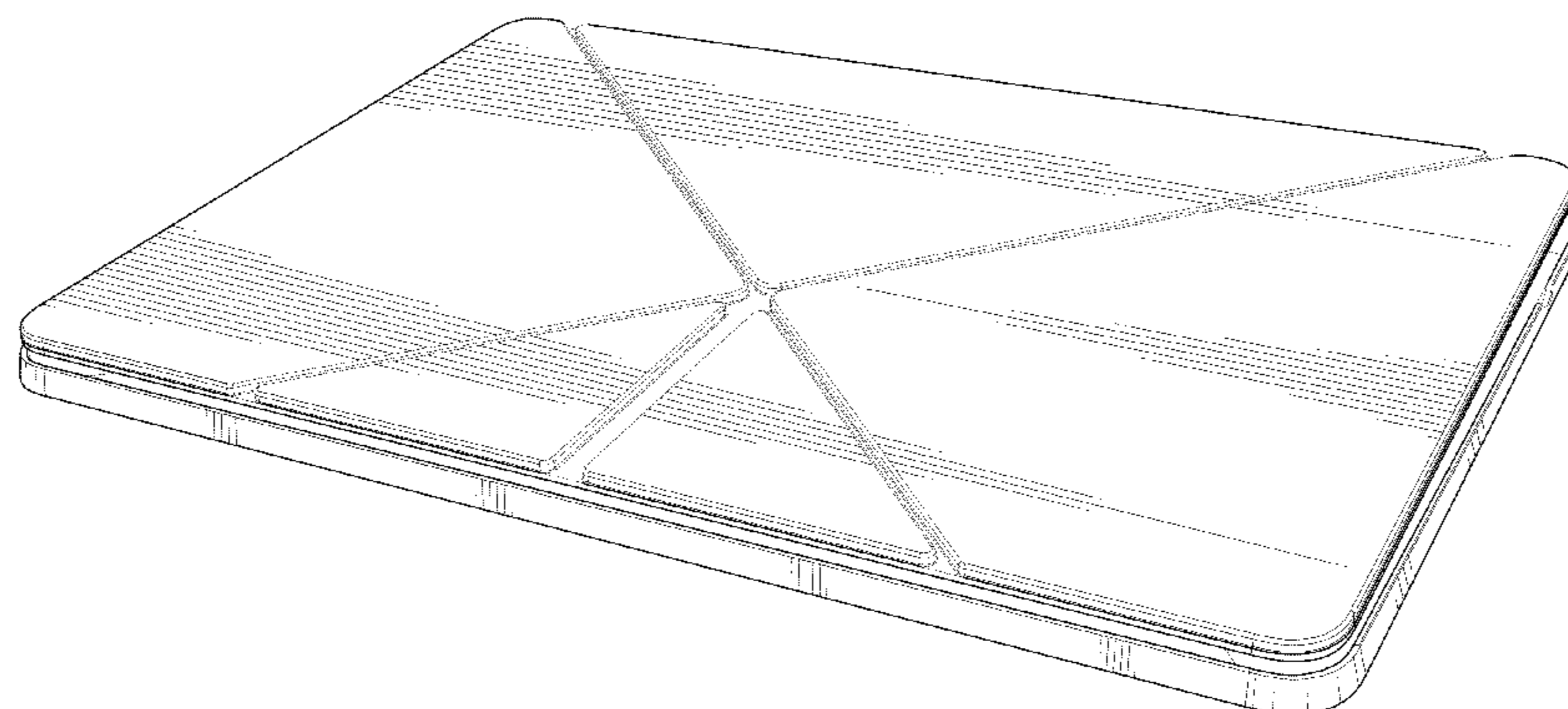
The ornamental design for an electronic device cover, as
shown and described.

DESCRIPTION

FIG. 1 is a first perspective view of an electronic device cover
for holding an electronic device, taken from above;
FIG. 2 is a second perspective view of the electronic device
cover of FIG. 1, taken from below;
FIG. 3 is a top plan view of the electronic device cover of FIG.
1;
FIG. 4 is a bottom plan view of the electronic device cover of
FIG. 1;
FIG. 5 is a front elevation view of the electronic device cover
of FIG. 1;
FIG. 6 is a back elevation view of the electronic device cover
of FIG. 1;
FIG. 7 is a right-side elevation view of the electronic device
cover of FIG. 1; and,
FIG. 8 is a left-side elevation view of the electronic device
cover of FIG. 1.

The broken lines are directed to unclaimed portions and form
no part of the claimed design.

1 Claim, 6 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

7,318,521 B2 1/2008 Lau
 7,414,833 B2 * 8/2008 Kittayapong 361/679.27
 D581,865 S 12/2008 Koza
 7,735,644 B2 * 6/2010 Sirichai et al. 206/320
 D658,187 S * 4/2012 Diebel D14/440
 D658,188 S * 4/2012 Diebel D14/440
 D663,304 S 7/2012 Akana et al.
 8,230,992 B2 * 7/2012 Law et al. 206/320
 8,235,208 B2 8/2012 Sirichai et al.
 8,245,843 B1 * 8/2012 Wu 206/320
 8,312,991 B2 * 11/2012 Diebel et al. 206/45.24
 D671,948 S * 12/2012 Akana et al. D14/440
 D672,353 S * 12/2012 Liu D14/440
 D672,781 S 12/2012 Lu
 D673,158 S 12/2012 Yang et al.
 D675,625 S * 2/2013 Hasbrook et al. D14/440
 D678,260 S * 3/2013 Bau D14/250
 D679,279 S 4/2013 Yang et al.
 D679,715 S * 4/2013 Akana et al. D14/440
 8,424,830 B2 * 4/2013 Yang et al. 248/459
 D681,641 S * 5/2013 Van Den Nieuwenhuizen
 et al. D14/440
 D682,836 S * 5/2013 Akana et al. D14/440
 D682,838 S * 5/2013 Akana et al. D14/440
 D683,141 S * 5/2013 Symons D6/310
 D687,438 S * 8/2013 Lu D14/440
 D690,305 S * 9/2013 Wen D14/440
 D690,702 S * 10/2013 Chung D14/440
 D691,142 S * 10/2013 Diebel D14/440
 D691,145 S 10/2013 Nam-Su
 D691,611 S 10/2013 Kirzinger
 D692,434 S 10/2013 Kim
 D693,823 S * 11/2013 Chen et al. D14/440
 D695,296 S * 12/2013 Hsu D14/440
 D696,253 S * 12/2013 Akana et al. D14/345
 D696,256 S * 12/2013 Piedra et al. D14/440
 D696,669 S * 12/2013 Akana et al. D14/440
 8,640,864 B2 * 2/2014 Chen et al. 206/45.2
 8,657,112 B2 * 2/2014 Igarashi 206/320
 D701,205 S * 3/2014 Akana et al. D14/345
 D702,673 S * 4/2014 Murchison et al. D14/250
 D704,689 S * 5/2014 Chang D14/250
 D704,693 S * 5/2014 Kim D14/250
 D706,270 S * 6/2014 Akana et al. D14/440
 D706,783 S * 6/2014 Almodova D14/440
 D707,229 S * 6/2014 Almodova D14/440
 8,757,375 B2 * 6/2014 Huang 206/320
 D708,838 S * 7/2014 Lee D3/201

8,763,795 B1 * 7/2014 Oten et al. 206/45.23
 8,766,921 B2 * 7/2014 Ballagas et al. 345/168
 8,773,353 B2 * 7/2014 Wei 345/156
 8,783,458 B2 * 7/2014 Gallagher et al. 206/320
 D710,859 S * 8/2014 Mecchella et al. D14/440
 8,797,132 B2 * 8/2014 Childs et al. 335/219
 2003/0034263 A1 * 2/2003 D'Hoste 206/320
 2008/0302687 A1 * 12/2008 Sirichai et al. 206/320
 2009/0159763 A1 * 6/2009 Kim 248/174
 2011/0266194 A1 * 11/2011 Bau 206/736
 2011/0290687 A1 * 12/2011 Han 206/320
 2012/0194448 A1 8/2012 Rothkopf
 2012/0211377 A1 * 8/2012 Sajid 206/216
 2012/0211613 A1 * 8/2012 Yang et al. 248/174
 2012/0305413 A1 * 12/2012 Chung 206/45.23
 2012/0308981 A1 * 12/2012 Libin et al. 434/362
 2013/0015088 A1 * 1/2013 Wu 206/320
 2013/0020216 A1 * 1/2013 Chiou 206/320
 2013/0140203 A1 * 6/2013 Chiang 206/320
 2013/0213838 A1 * 8/2013 Tsai et al. 206/320
 2013/0214661 A1 * 8/2013 McBroom 312/325
 2013/0241381 A1 * 9/2013 Hyneczek et al. 312/240
 2013/0264459 A1 * 10/2013 McCosh et al. 248/688

OTHER PUBLICATIONS

Translated the Japanese Office Action mailed Aug. 8, 2014 for Japanese design application No. 2014-004976, a counterpart foreign application of design U.S. App. No. 29/467,667, 3 pages.
 Translated the Japanese Office Action mailed Aug. 8, 2014 for Japanese design application No. 2014-004975, a counterpart foreign application of US design patent No. D710859, 3 pages.
 The Indian Office Action mailed May 21, 2014 for Indian design application No. 261091, a counterpart foreign application of design U.S. Appl. No. 29/467,672, 11 pages.
 The Indian Office Action mailed May 21, 2014 for Indian design application No. 261089, a counterpart foreign application of design U.S. Appl. No. 29/467,661, 11 pages.
 The Canadian Office Action mailed Aug. 27, 2014 for Canadian design application No. 155341, a counterpart foreign application of design U.S. Appl. No. 29/467,667, 1 page.
 The Canadian Office Action mailed Aug. 27, 2014 for Canadian design application No. 155340, a counterpart foreign application of US design patent No. D710859, 1 page.
 The Canadian Office Action mailed Aug. 27, 2014 for Canadian design application No. 155339, a counterpart foreign application of design U.S. Appl. No. 29/467,672, 1 page.
 Office action for U.S. Appl. No. 29/467,672, mailed on Sep. 24, 2014, Mecchella et al., "Electronic Device Cover," 5 pages.

* cited by examiner

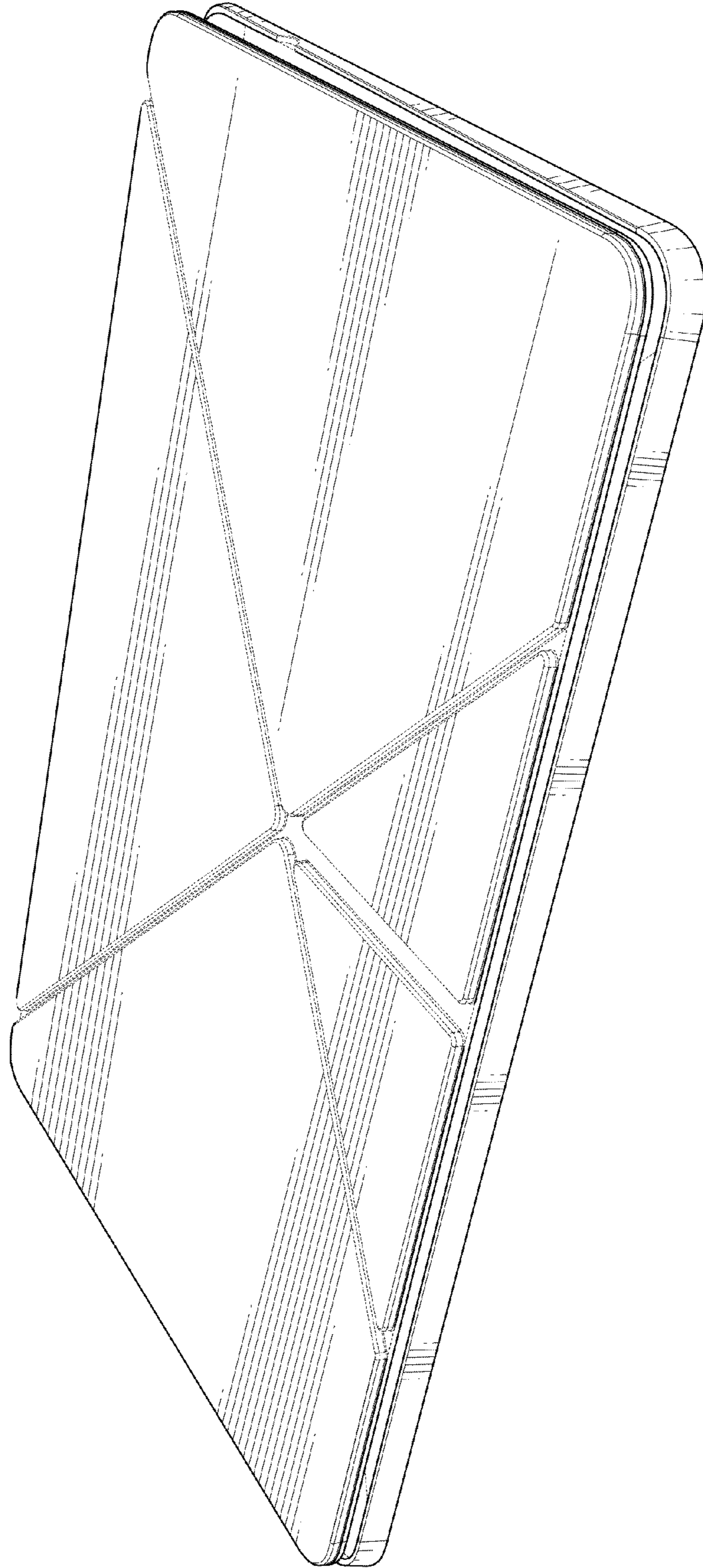


FIG. 1

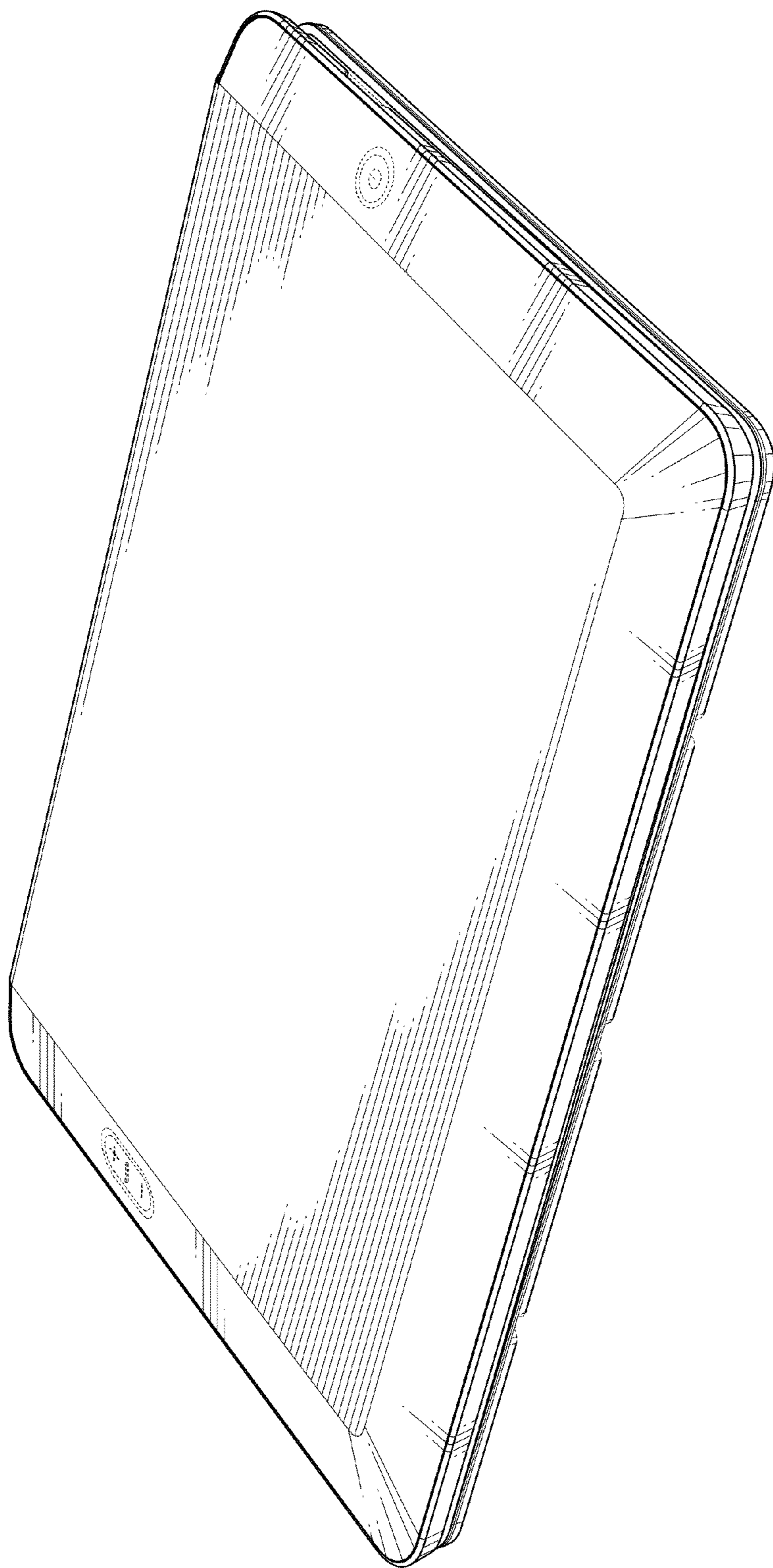


FIG. 2

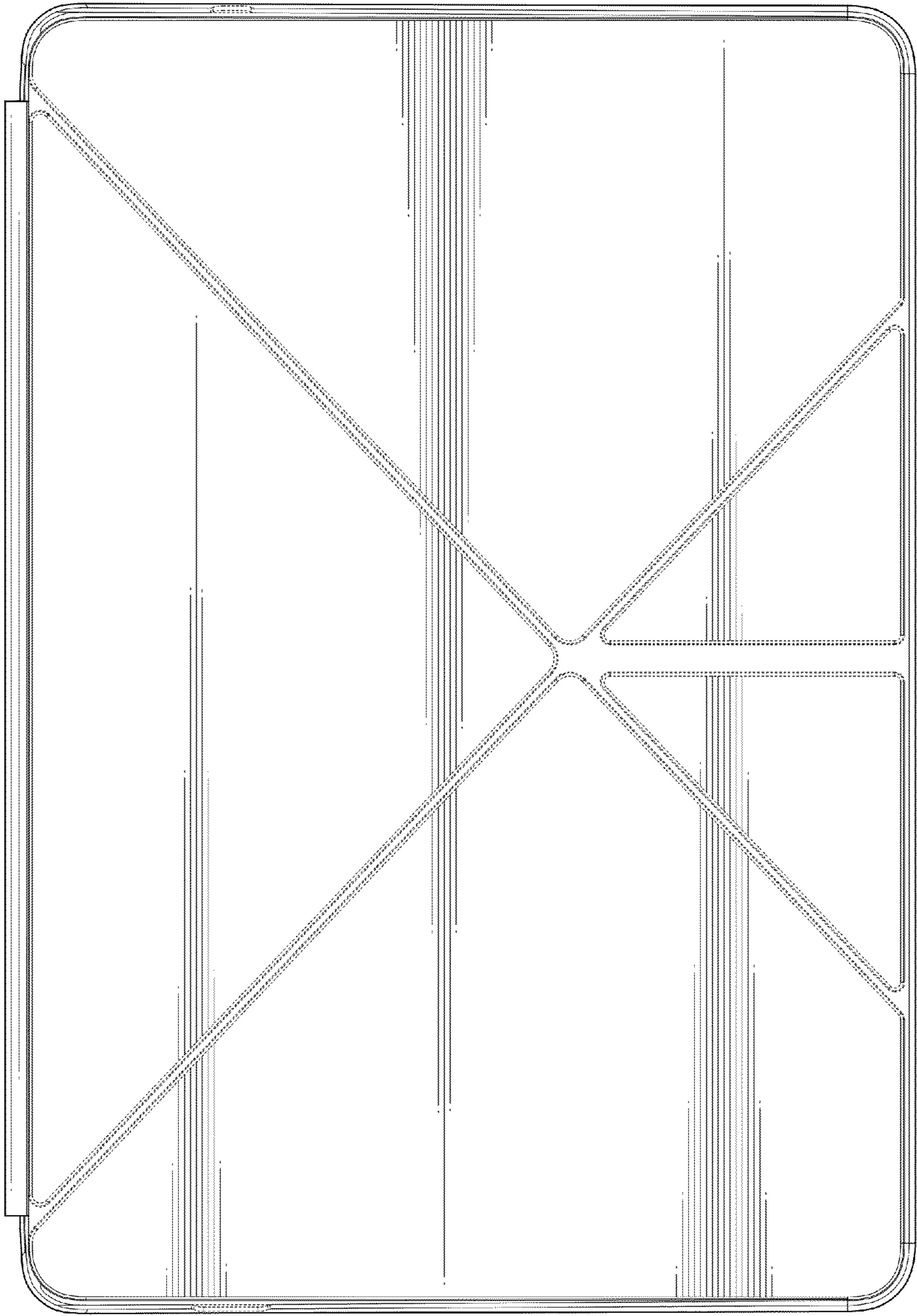


FIG. 3

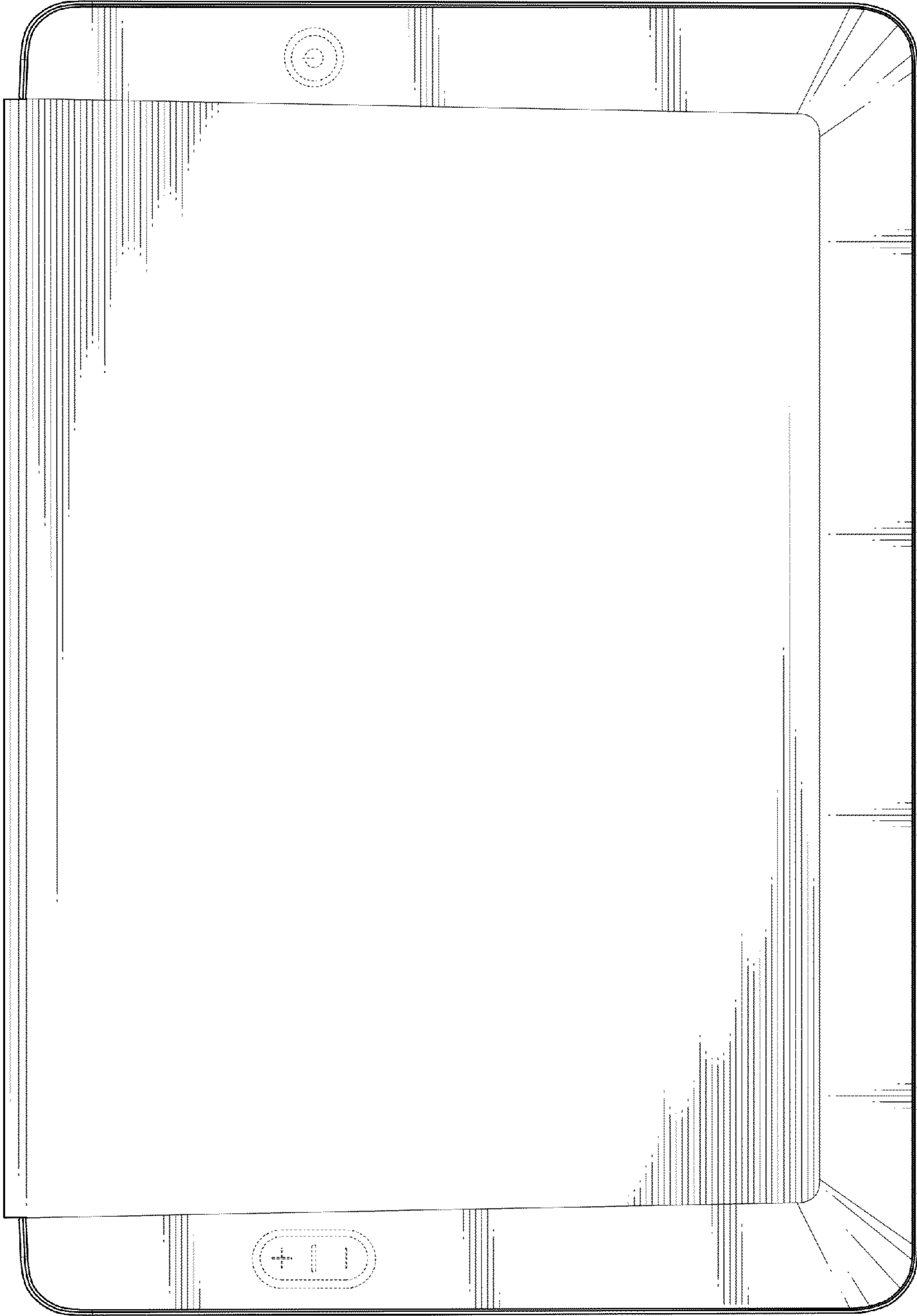


FIG. 4

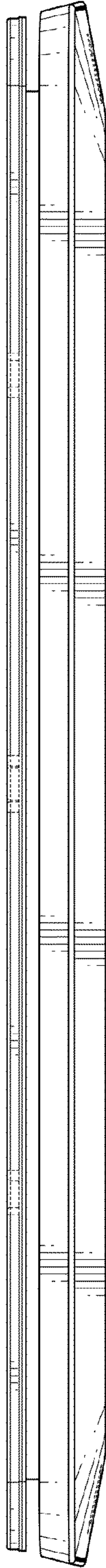


FIG. 5

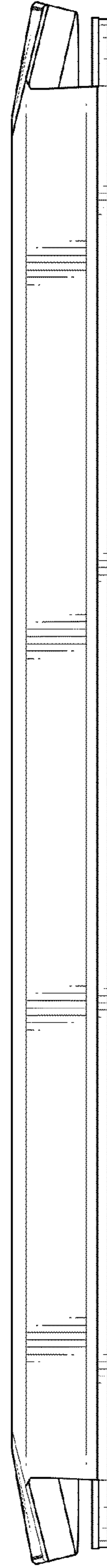


FIG. 6

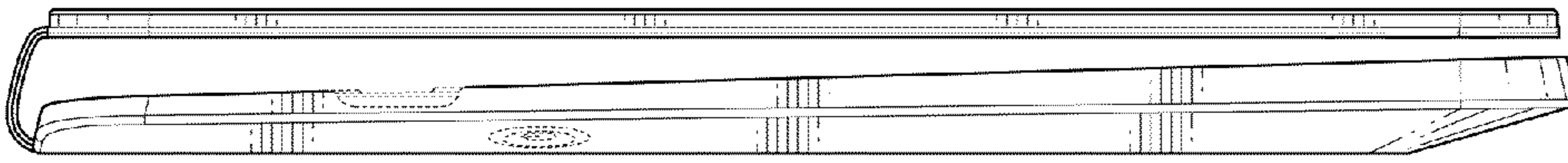


FIG. 8

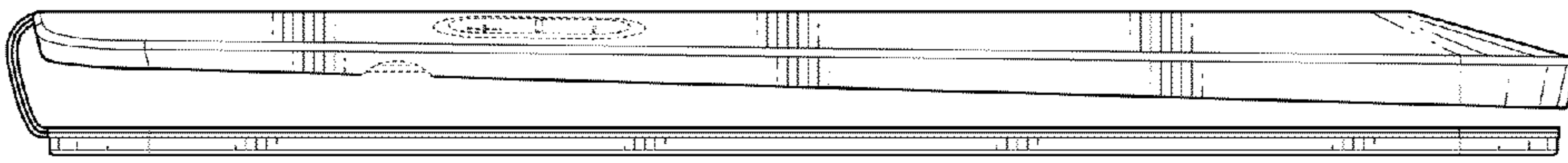


FIG. 7